

Purpose

This declaration is intended to disclose substances contained in THAT Corporation's 16xx-U series integrated circuits. The table below lists Materials and Substances included in the Joint Industry Guide (JIG) - Material Composition Declaration Guide, released on September 19, 2003. This covers all materials defined in Article 4.1 of the European Directive 2011/65/EU, of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS 2 Directive).

Materials Declaration

| Leadframe Plating: NiPdAu | | | | Percent by weight of homogenous material ¹ | | | | |
|--------------------------------------|---------------------------|------------------|--------------------------------------|---|-------------------------|-----|---------------------------|-----------|
| Controlled Chemicals | | Threshold Limits | | IC itself | Shipping Container | | | |
| | | RoHS | JIG | | Box | Bag | Tube | End Plugs |
| Cadmium | Elemental | 0.01% | 0.0075%, and not intentionally added | <0.00003% | ND ² | ND | ND | ND |
| | Cd Compounds | | | ND | ND | ND | ND | ND |
| Lead | Elemental | 0.10% | 0.10%, and not intentionally added | <0.03% | ND | ND | ND | ND |
| | Pb Compounds | | | ND | ND | ND | ND | ND |
| Mercury | Elemental | | | <0.0001% | ND | ND | ND | ND |
| | Hg Compounds | | | ND | ND | ND | ND | ND |
| Hexavalent Chromium | Elemental | | | <0.00001% | ND | ND | ND | ND |
| | Cr ₆ Compounds | | | ND | ND | ND | ND | ND |
| Polybrominated biphenyls (PBB) | | | | ND | ND | ND | ND | ND |
| Polybrominated diphenylethers (PBDE) | | | | ND | ND | ND | ND | ND |
| Perfluorooctane sulfonates (PFOS) | | | | ND | ND | ND | ND | ND |
| Polychlorinated biphenyls (PCB) | | | | Not Regulated | Not intentionally added | ND | ND | ND |
| Polychlorinated naphthalenes (PCN) | | ND | ND | | | ND | ND | |
| Polychlorinated terphenyls (PCT) | | ND | ND | | | ND | ND | |
| Chlorinated parafins (CP) | | ND | ND | | | ND | ND | |
| Other Chlorinated Compounds | | <0.0003% | ND | | | ND | ND | ND |
| Azo Compounds | | ND | ND | | | ND | ND | |
| Tributyltin compounds | | ND | ND | | | ND | ND | |
| Triphenyltin compounds | | ND | ND | ND | ND | | | |
| Other brominated organic compounds | | Not Regulated | 0.01% | ND | ND | ND | ND | |
| Antimony | | | | ND | ND | ND | ND | |
| Other antimony compounds | | | | ND | ND | ND | ND | |
| Asbestos | | | | ND | ND | ND | ND | |
| Polyvinyl chloride (PVC) and blends | | | | ND | ND | ND | <0.001% of Vinyl Chloride | |

Notes

1. A material is homogeneous if its compound concentration (as % wt) is not changed by mechanical disjoining (cutting, grinding, etc.). For example, in an integrated circuit, the homogenous materials would be the ink, mold compound, gold wires, die, die attach epoxy, base lead frame material and lead frame surface finish. Laser-marked parts may not include ink.

2. ND - None Detected.

Disclaimer

This information has been collected from THAT Corporation's manufacturing facilities and our worldwide supply chain. To the best of our knowledge, it is correct as of the date indicated on this page. However, we cannot guarantee its completeness or accuracy as some information has been derived from data sources outside the company.